



Multiband GNSS Front End

Part No: TFM.110A

Description

Surface Mount GNSS Front End Active Electronics

Covering the full Multiband GNSS Spectrum excluding the L-Bands

Features:

Two-stage LNA providing >25 dB Gain across all bands

Low Noise Figure: <3.5 dB in low bands and <4.0 dB in high bands

Vin = +1.8 to +5.5 VDC

Easy to integrate surface-mount

Dimensions: 15 x 15 x 2.7 mm

RoHS & Reach Compliant



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1. Introduction



The Taoglas TFM.110A is a surface-mount active electronics GNSS front end which covers L1/L2/L5 for multiband multi-constellation high-precision applications. The TFM.110A features a SAW/LNA/SAW/LNA topology in the signal path to prevent unwanted out-of-band interference from overdriving the GNSS LNAs or receiver. The SAW filters have been carefully selected and placed to provide excellent out-of-band rejection while also maintaining low noise figure.

Many currently available dual-band GNSS receivers require additional RF circuits between the antenna and the receiver to properly set the overall system noise figure. This requires additional development time for an otherwise simple integration. Many organizations don't have the RF expertise to effectively design such a solution. The TFM.110 captures the required additional RF circuits in modular form, allowing the designer to simply place the TFM.110 between their GNSS antenna and GNSS receiver.

The TFM.110 offers > 25 dB gain across all applicable bands while maintaining a high Input P1dB of-25 dBm or better. Noise Figure is < 3.5 dB in the low bands and < 4.0 dB in the high bands. A wide input voltage of +1.8 to +5.5 VDC allows for easy integration in most GNSS systems.

TFM.110A Features & Benefits:

- Ease-of-integration Single-package solution combines impedance matching, filter efficiency and low noise design for easy, drop-in use with any antenna or GNSS receiver
- Low-noise System Design Integrated pre-filters deliver exceptional out-of-band rejection across multiple band configurations and neighboring interference to properly set noise figure
- Dual-gain Stage Architecture Cascaded LNAs, pre-filters and optimized impedance matching deliver sufficient gain to the GNSS receiver without signal-to-noise overload
- Low-profile Form Factor Small footprint and low-profile design saves valuable real estate without the need for external components and routing
- \bullet Accelerated Development Cycles -2+ years of development by antenna and RF design experts, delivering the highest levels of integration, manufacturability and robustness in a single package

For further information, please contact your regional Taoglas customer support team.



2. Specification

			Ele	ectrical					
Frequency (MHz)	1166	1176	1186	1197	1227	1249	1559	1575.42	1606
Noise Figure (dB)*	2.9	2.7	2.6	2.5	3.1	3.1	3.3	3.1	3.6
Gain (dB)	29	30	30	31	30	31	27	26	25
Group Delay (ns)	22	20	18	19	17	23	16	16	23
Input P1dB (dBm)	-23	-24	-24	-24	-22	-23	-18	-18	-17
Input Return Loss (dB)	-10	-11	-12	-13	-11	-14	-11	-11	-13
Output Return Loss	-9	-9	-10	-14	-14	-17	-24	-31	-25
Vin				+1	.8 to +5.5 V	DC			
Typical Current (@1.8V)					7.5 – 9.0mA	A			

^{*}Note: Tested on evaluation board. Board losses removed.

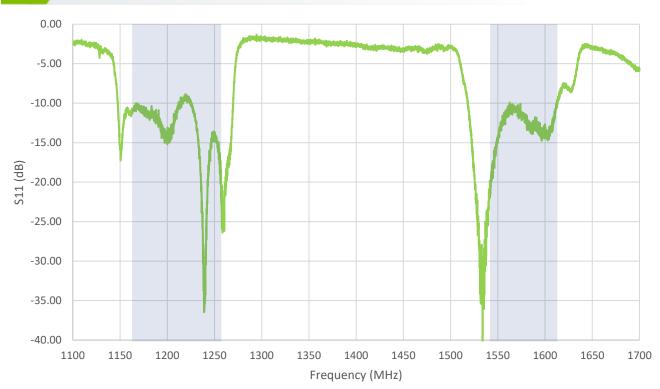
	Mechanical
Height	2.76mm
Planar Dimension	15.50 x 15.50mm

	Environmental
Temperature Range	-40°C to 85°C
RoHS Compliant	Yes
REACH Compliant	Yes

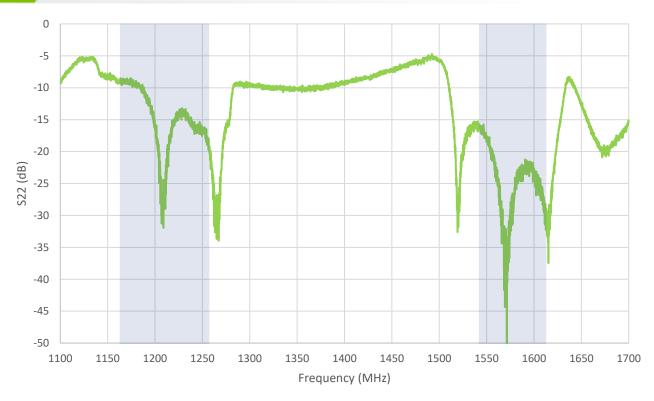


3. FEM Characteristics

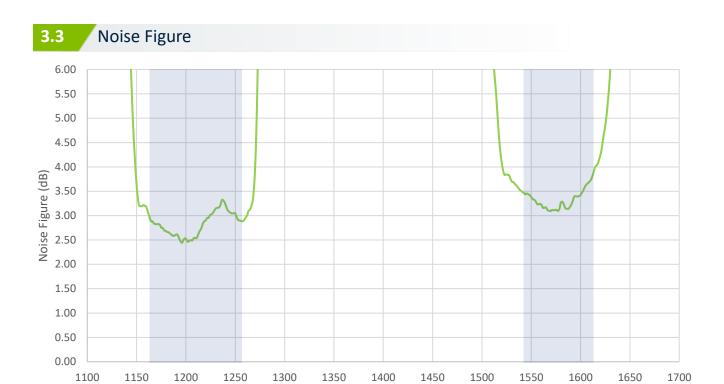
3.1 Input Return Loss



3.2 Output Return Loss

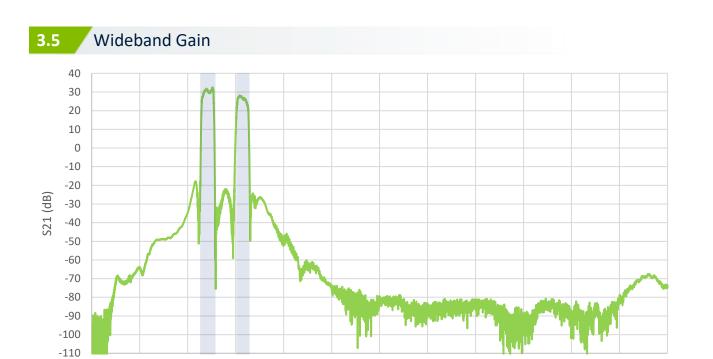












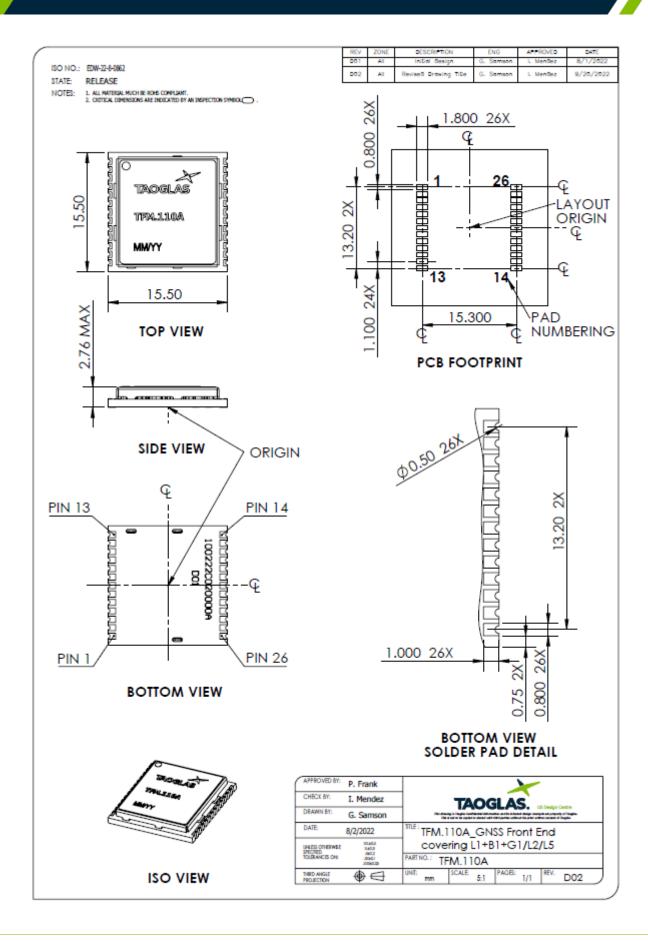
Frequency (MHz)

3.6 Group Delay Group Delay (ns)

Frequency (MHz)

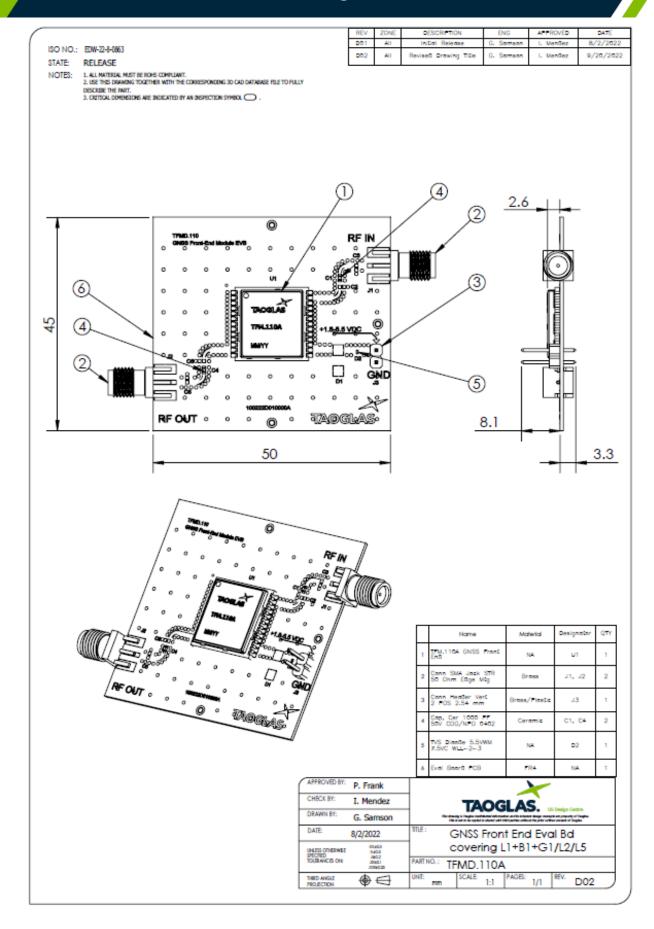


4. Mechanical Drawing





Eval Board Mechanical Drawing





6. Module Integration



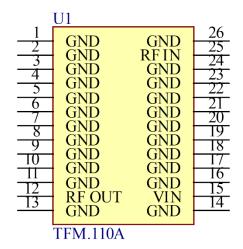




6.1 Schematic Symbol and Pin Definitions

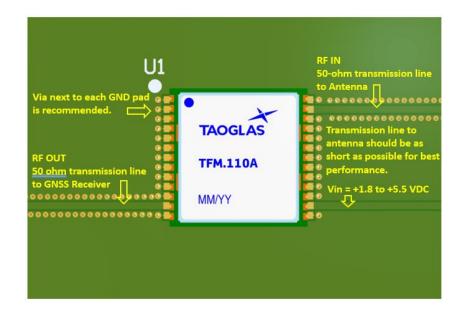
The circuit symbol for the TFM.110A is shown below. The front-end module has 26 pins as indicated below.

Pin	Description
1-11, 13-14, 16- 24, 26	Ground
12	Signal Output
15	Voltage Input
25	Signal Input



6.2 Module Integration

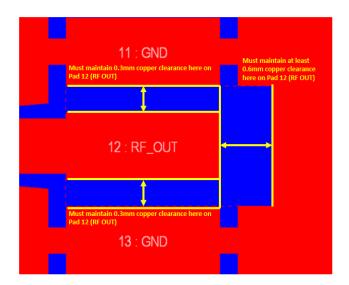
The TFM.110A should be placed as close to the signal input and output as possible to shorten the length of the transmission lines. The RF IN/OUT traces must maintain a 50 Ohm transmission line. A Pi Matching Network is recommended for the RF IN transmission line, the values and components for the matching circuit will depend on the tuning needed. Ground vias should be placed beside each ground pad and the DC Voltage input should be between +1.8 & +5.5 VDC. It's recommended that the DC Voltage input should be coupled with a 100pF Capacitor.

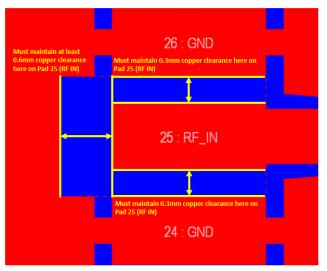




6.3 PCB Clearance

The footprint and clearance on the PCB must comply with the front-end module's specification. The PCB layout shown in the diagram below demonstrates the TFM.110A clearance area for Pin 12 (RF OUT Pad) & Pin 25 (RF IN Pad). The copper keep out area only applies to the same layer the TFM110.A was placed.





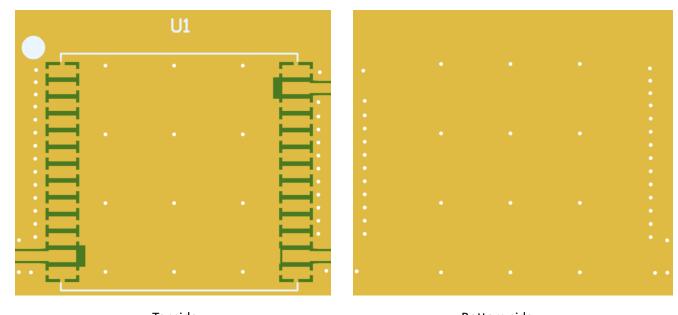
Pin 12 (RF OUT PAD)

Pin 25 (RF IN PAD)



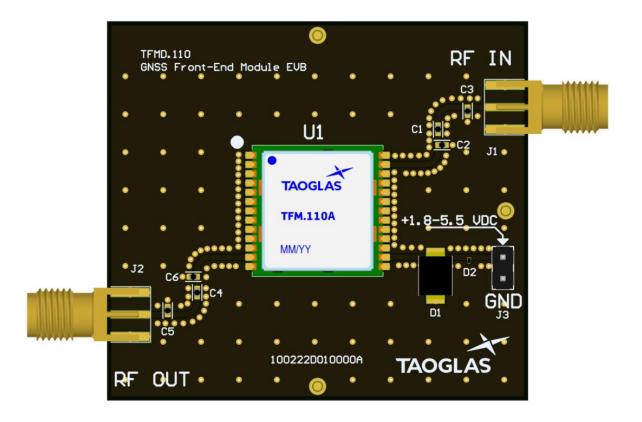
6.4 PCB Layout

The footprint and clearance on the PCB must comply with the front-end module's specification. The PCB layout shown in the diagram below demonstrates the TFM.110A footprint.



Topside Bottom side

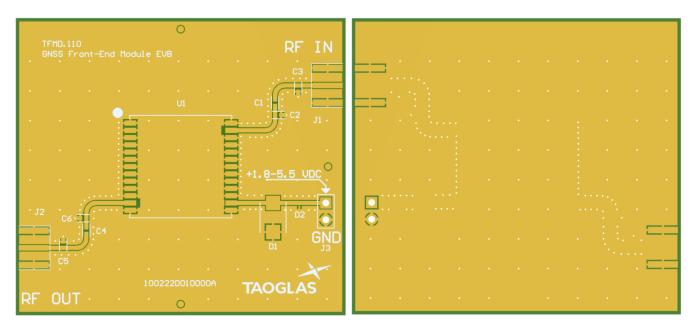
6.5 Evaluation Board





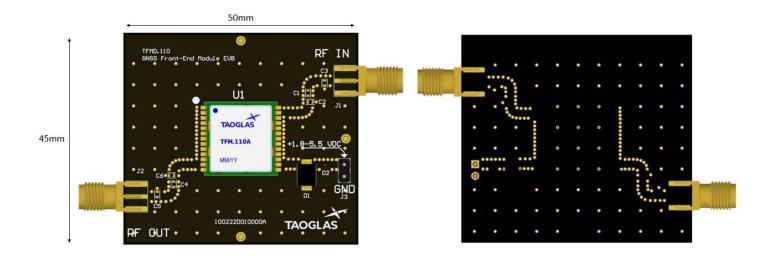
6.6 Demonstration Board Layout

The footprint and clearance on the PCB must comply with the front-end module's specification. The PCB layout shown in the diagram below demonstrates the TFM.110A footprint.



Topside Bottom side

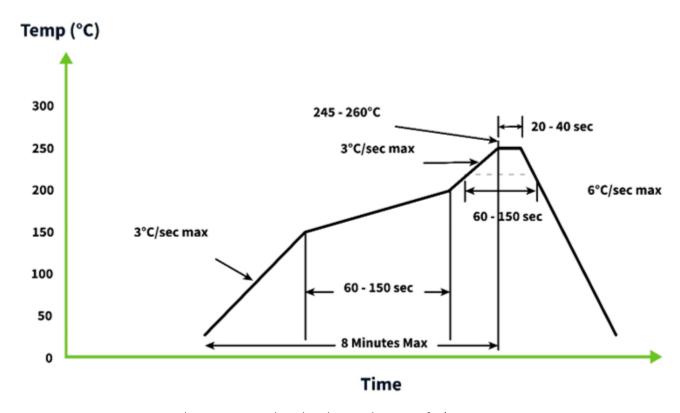
6.7 Evaluation Board Dimensions





7. Solder Reflow Recommendations

The TFM.110A can be assembled by following the recommended soldering temperatures are as follows:



*Temperatures listed within a tolerance of +/- 10º C

Smaller components are typically mounted on the first pass, however, we do advise mounting the TFM.110A when placing larger components on the board during subsequent reflows.



8. Packaging

800 PCS / Reel SPQ Label



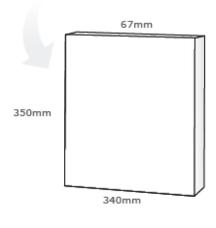
800 PCS / Vacuum bag 2 PCS / 3g Desiccant 1 PCS / Humidity test paper SPQ Label



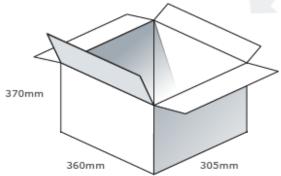
Caution Label Product Label SPQ Label



1 PCS / Box Box(mm): 350x340x67 Weight (Kg): 2 SPQ Label



3200 PCS / Carton Carton(mm): 370x360x305 Weight (Kg): 8.8 Carton Label





SPE-22-8-149 - TFM.110.A

Revision: D (Current	Version)
Date:	2023-08-18
Notes:	Added power consumption to spec table
Author:	Gary West

Previous Revisions

Revision: C	
Date:	2023-06-09
Notes:	Updated Module Integration Guide Added Packaging & Solder Reflow Profile
Author:	Gary West
Revision: B	2022 40 20
Date: Notes:	2022-10-28 Added antenna integration guide
Notes.	Added afferma integration guide
Author:	Gary West
Revision: A (Origina	al First Release)
Date:	2022-09-26
Notes:	Initial Release
Author:	Gary West